SUPPLEMENTARY INFORMATION

Fully solution-processable fabrication of multi-layered circuits on flexible substrate using laser

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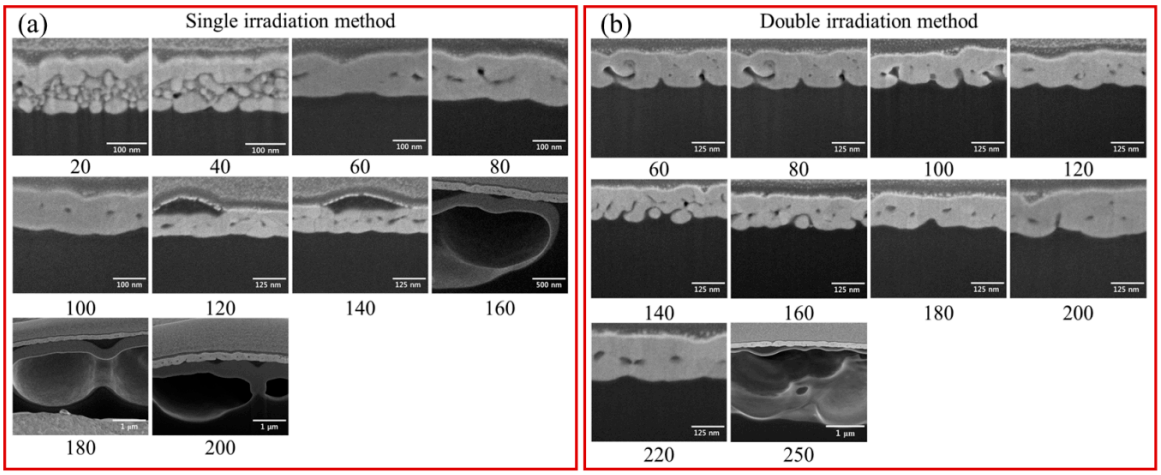
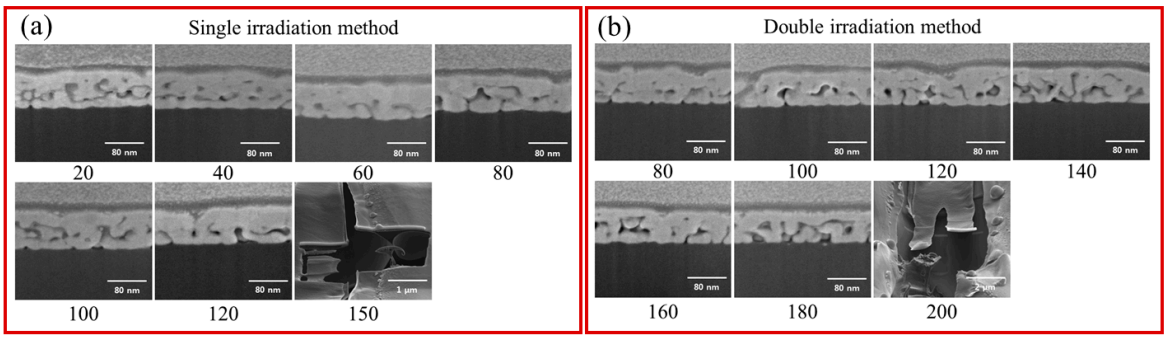
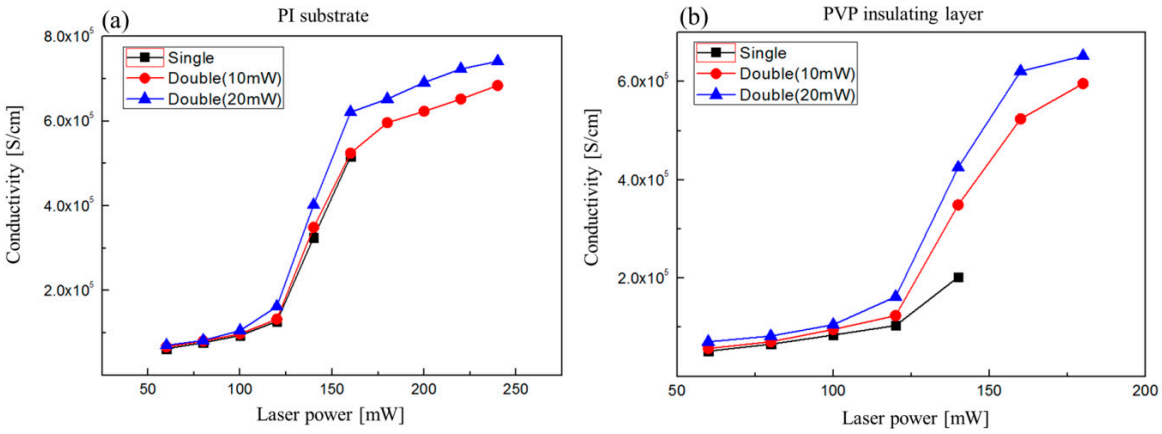


Supplementary Fig. S1. Cross-sectional SEM image of electrode lines using (a) single irradiation method and (b) double irradiation method with the surface sintering of laser power of 20 mW at various laser powers. All printed patterns were fabricated on PI substrate.



Supplementary Fig. S2. Cross-sectional SEM image of electrode lines using (a) single irradiation method and (b) double irradiation method with the surface sintering of laser power of 20 mW at various laser powers. All printed patterns were fabricated on PVP insulating layer.



Supplementary Fig. S3. Electric conductivity versus laser power on (a) PI substrate and (b) PVP insulating layer.